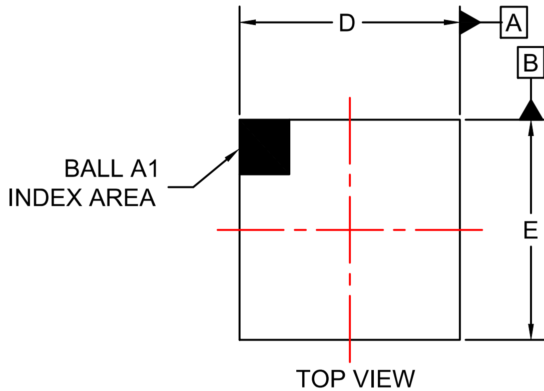
WLCSP36 2.43x2.43x0.599
CASE 567XH
ISSUE O

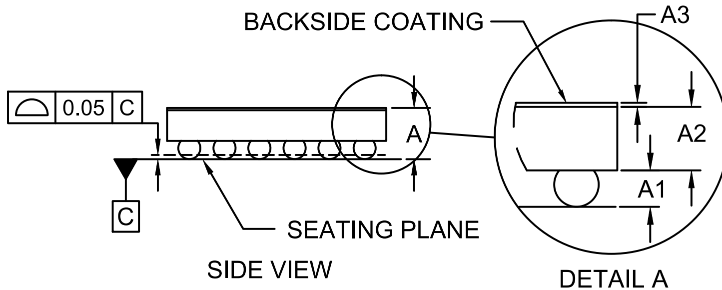
DATE 12 FEB 2019

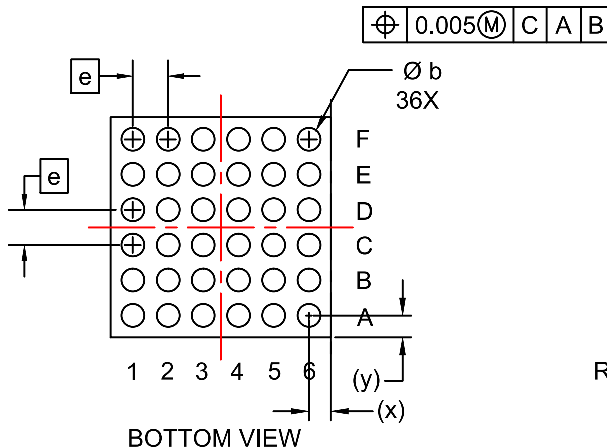


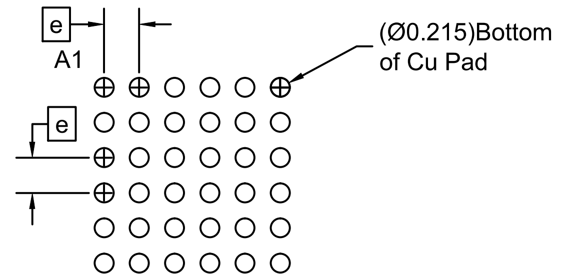
NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DATUM C APPLIES TO THE SPHERICAL CROWN OF THE SOLDER BALLS

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.558	0.599	0.640
A1	0.174	0.194	0.214
A2	0.362	0.380	0.398
A3	0.022	0.025	0.028
b	0.240	0.260	0.280
D	2.400	2.430	2.460
E	2.400	2.430	2.460
e	0.40 BSC		
x	0.200	0.215	0.230
y	0.200	0.215	0.230







RECOMMENDED MOUNTING FOOTPRINT
(NSMD PAD TYPE)

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